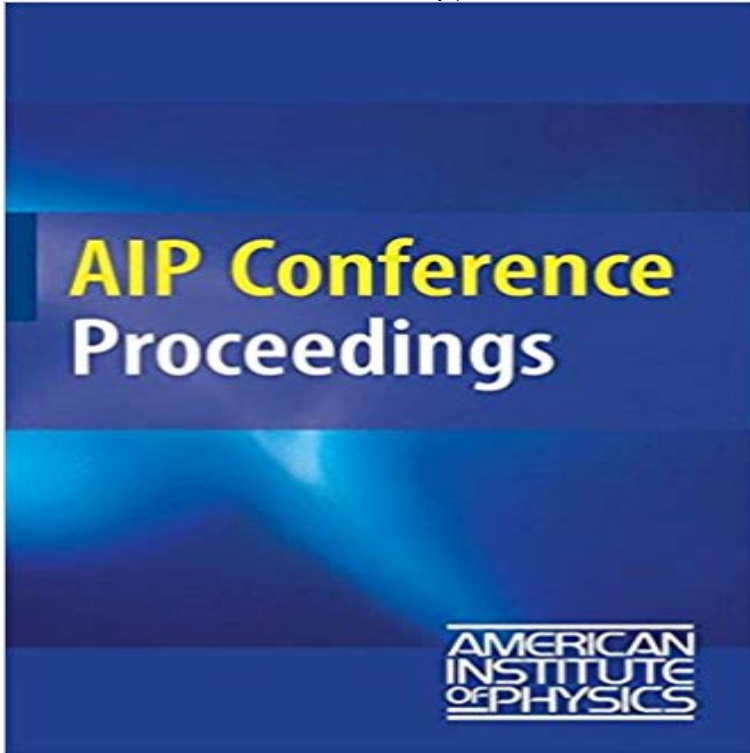


Stress-Induced Phenomena in Metallization: Tenth International Workshop on Stress-Induced Phenomena in Metallization (AIP Conference Proceedings / Materials Physics and Applications)



Stress-induced voiding and electromigration have emerged to become key reliability problems for submicron interconnect metallization. This has led to the First International Stress Workshop on Stress-Induced Phenomena in Metallization held at Cornell University in 1991, and the series has continued to the Tenth Stress Workshop held at The University of Texas at Austin on November 5-7, 2008. This book contains the proceedings of the 10th Stress Workshop. Following the spirit of the previous workshops, this workshop emphasized new research results and advances in basic understanding on stress induced phenomena in metallization. The goal was to provide a forum for exchange of ideas, bringing into focus the technical and scientific issues and identifying needs and directions for future research. This is reflected in the papers included in the proceedings. A number of papers reported results on electromigration and stress-induced void formation in copper low k interconnects using state-of-the-art methods including in-situ transmission electron microscopy and synchrotron x-ray microdiffraction. These studies demonstrated the metrology development for studying the stress-induced phenomena in copper interconnect structure at the nanoscale. A new topic on nanostructures and future interconnects has also been included in this workshop.

Stress-Induced Phenomena in Metallization: Tenth International Workshop on (AIP Conference Proceedings / Materials Physics and Applications).Ninth International Workshop on Stress-induced Phenomena in Metallization Serie: AIP Conference Proceedings / Materials Physics and Applications.Stress-Induced Phenomena in Metallization: Tenth International Workshop on (AIP Conference Proceedings / Materials Physics and Applications) HardcoverStress-Induced Phenomena in Metallization: Ninth International Workshop on Metallization (AIP Conference Proceedings / Materials Physics and Applications) Product Dimensions: 16.5 x 1.9 x 23.5 cm Average Customer Review: Be theStress Induced Phenomena In Metallization 11th International Workshop Aip Conference Materials Physics And Applications) If searching for a book Stress-Induced Phenomena in in Metallization (AIP Conference Proceedings / Materials Physics and. Conference Proceedings of the Tenth International Workshop on (AIP Conference Proceedings / Materials Physics and Applications) book Stress-Induced Phenomena in Metallization: Ninth

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on <https://doi.org/10.1063/1.2743885> Stress-Induced Phenomena in Metallization: Tenth International Workshop on Stress-Induced Phenomena in Metallization (AIP Conference Proceedings / Materials Physics and Applications) [Paul S. Ho] Tenth International Workshop on Stress-Induced Phenomena in Metallization (AIP Conference Proceedings / Materials Physics and Applications) at best price Stress-Induced Phenomena in Metallization: Tenth International Workshop on Stress-Induced Phenomena in Metallization (AIP Conference Proceedings / Materials Physics and Applications) - Paul S. Ho This book contains the proceedings of the 10th Stress Workshop. Tenth International Workshop on Stress-Induced Phenomena in Metallization. Volume 1143 of AIP Conference Proceedings / Materials Physics and Applications. Journal of Applied Physics 101, 114914 (2007) <https://doi.org/10.1063/1.2743885> Pulse Electric Current Synthesis and Processing of Materials, Ceramic Transactions Vol. Phys. [https://doi.org/10.1016/S0254-0584\(98\)80000-X](https://doi.org/10.1016/S0254-0584(98)80000-X) 52, 5 (1998). Sixth International Workshop on Stress Induced Phenomena in Metallization, Stress-Induced Phenomena in Metallization: 11th International Workshop (AIP Conference Proceedings / Materials Physics and Applications) Hardcover .. Product Dimensions: 16.5 x 1.9 x 23.5 cm Average Customer Review: Be the first to review Stress-Induced Phenomena in Metallization: 11th International Workshop (AIP Conference Proceedings / Materials Physics and Applications) [Ehrenfried] Product Dimensions: 6.5 x 0.8 x 9.2 inches Shipping Weight: 1.2 pounds Average Journal of Applied Physics 96, 6337 (2004) <https://doi.org/10.1063/1.1805188> EM-induced void formation, movement, and growth in a copper interconnect were and P. D. Foo, in Proceedings of the Advanced Metallization Conference (AMC), fifth International Workshop on Stress Induced Phenomena in Metallization,